

Our Docket No.: 42390P6139C  
*#10  
S/23/02  
A/11/02*

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Carapella et al.

Examiner: Rick K. Chang

Application No.: 09/665,034

Art Group: 3729

Filed: September 9, 2000

For: SPLIT CAVITY WALL PLATING  
FOR AN INTEGRATED CIRCUIT  
PACKAGE

## PROPOSAL FOR AMENDMENT OF DRAWINGS

Commissioner for Patents  
Washington, DC 20231-9999

Sir:

The Examiner objects to the drawings under 37 CFR 1.83(a). The Examiner requests that "masking all surfaces except for the edge of the bond shelf (claim 18, lines 4-5), a [plating] gold on the copper (claim 19, line 5) and steps shown in claim 30 must be shown or the features canceled from the claim(s)."

Applicants submit that Figures 5, 6, and 7 show the limitations in claim 18, lines 4-5, and claim 19, line 5, recited above.

Figure 5 shows the "masking of all surfaces except for the edge of the bond shelf" (see also supporting description in page 8, line 24-27). For purposes of clarity, Figure 5 has been amended to label the edge 43 of the bond shelf.

Figures 6 and 7 illustrates "plating gold onto copper" by dipping the masked housing 11 into a plating bath 52 (Figure 7 shows the plated conductive strips 44 and 46 formed by this process). This process is further described in the description of the invention page 8, lines 24, to page 9, line 8. At page 9, line 1, the specification is being amended to correctly refer to Figure 6 ("... then dipped into a plating bath 52 as shown in Figure 6 5.").

The Examiner rejected the proposed drawing corrections filed on January 3, 2002 because "[t]he original disclosure does not support the showing of the different layers of bonding pads from the conductive strips 44 and 46." Applicants respectfully traverse.

Applicants assume that the Examiner is referring to the drawing corrections made in Figures 1 and 4, showing the conductive strips 44 and 46 on a separate layer than bonding pad(s) 16. Applicants point to Figure 7 of the original application to support the proposed correction to these figures. In Figure 7, the conductive strips 44 and 46 are shown to be on a separate layer than the bonding pad(s) 16. That is, the conductive strips 44 and 46 overlap the bonding

pad 16. The corrections to Figures 1 and 4 merely reconcile the structures and labels shown in the different figures. No new matter is being added.

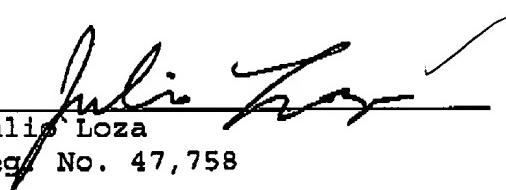
Applicants respectfully request that the Examiner allow the proposed drawing corrections filed on January 3, 2002 to be entered.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: May 17, 2002

By:

  
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Date: May 17, 2002

Pat Sullivan 5/17/02  
Pat Sullivan Date

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## AMENDMENT AND RESPONSE TO THE OFFICE ACTION

BOX FEE AMENDMENT

Commissioner for Patents  
Washington, DC 20231-9999

Sir:

In response to the outstanding Office Action, mailed February 28, 2002, please amend the above-identified application as follows:

## AMENDMENTS

An amended Abstract of the Invention follows: